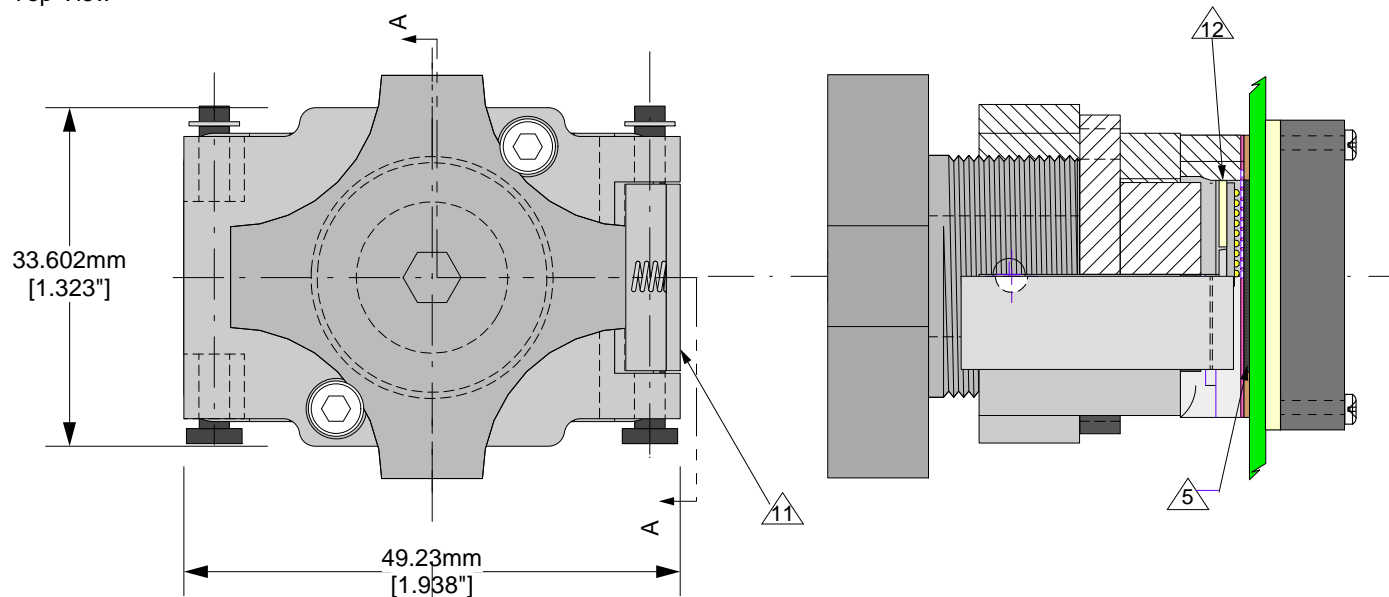
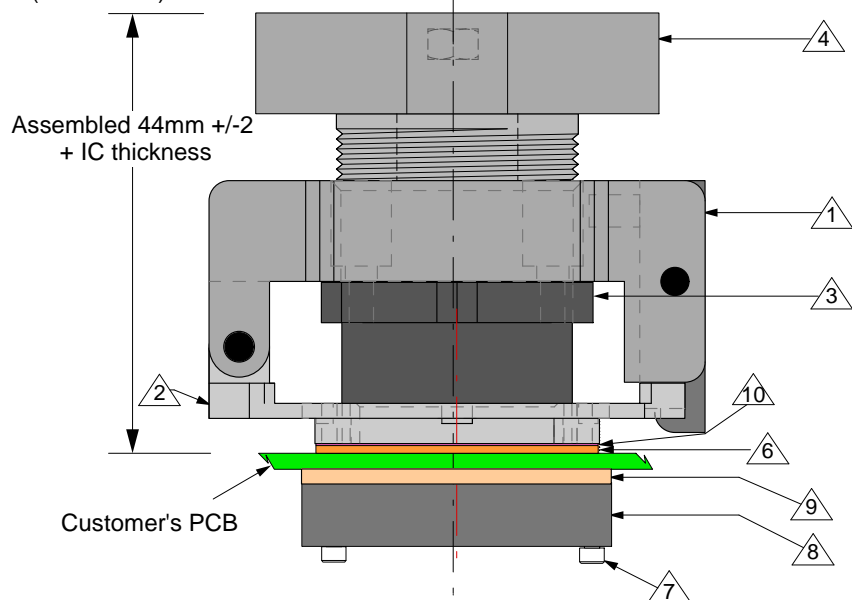


Top View



Side View
(Section AA)




Features

- Directly mounts to target PCB (needs tooling holes) with hardware
- Minimum real estate required
- Compression plate distributes forces evenly
- Clamshell lid

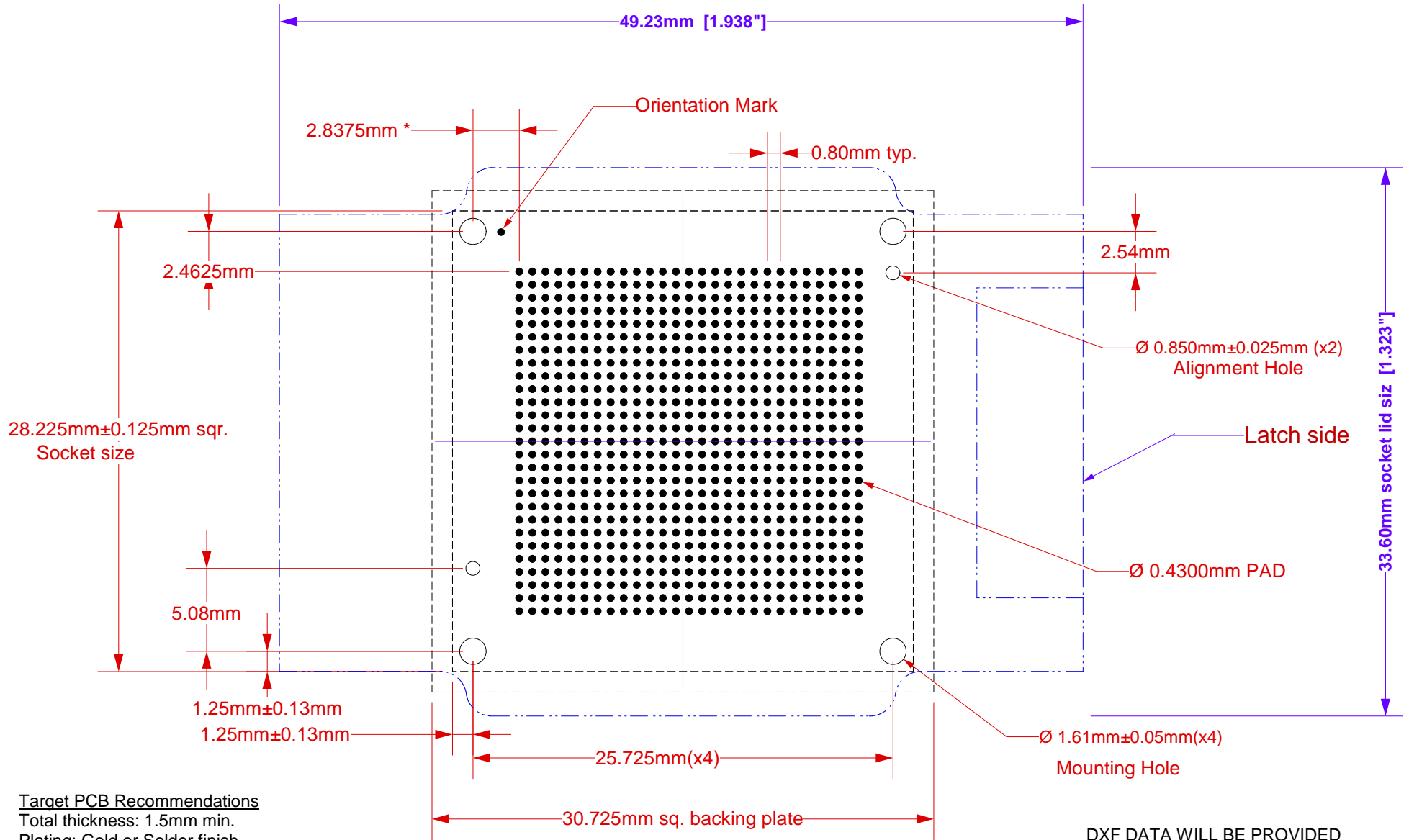
Materials:

- 1 Clam Shell Lid: Black anodized Aluminum. Height = 20 mm.
- 2 Socket Base: Black anodized Aluminum. Height = 6 mm.
- 3 Compression Plate: Black anodized Aluminum. Thickness = 12 mm.
- 4 Compression Screw: Clear anodized Aluminum. Height = 27 mm, Fluted Knob
Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- 5 Elastomer Guide: Non-clad FR4. Thickness = 0.725mm.
- 6 Socket Base Screw: Socket Head Cap Screw, alloy steel with black oxide finish, 0-80 Thread, 1/2" long.
- 7 Backing Plate: Black anodized Aluminum
- 8 Insulation Plate: Ultem
- 9 Ball Guide: Kapton polyimide.
- 10 Latch: Black anodized Aluminum.
- 11 IC frame: Ultem

| | | | | |
|---|--|-----------------------|---------------|--------|
|  | CG-BGA-4007 Drawing | Status: Released | Scale: 1.25:1 | Rev: A |
| | © 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com | Drawing: Vinayak R | Date: 3/1/10 | |
| | | File: CG-BGA-4007 Dwg | Modified: | |

All Tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.


***Note: BGA pattern is not symmetrical with respect to the mounting holes.**



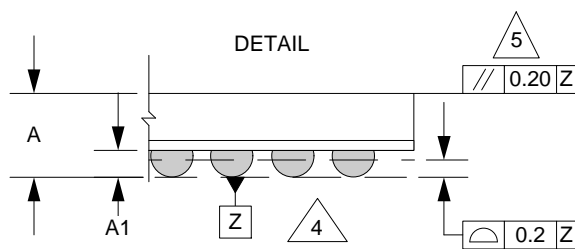
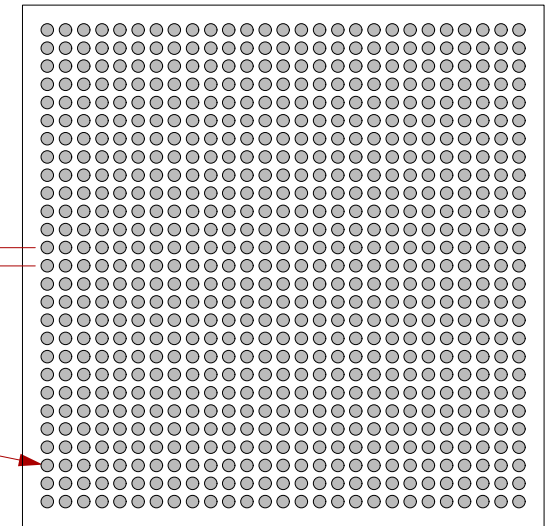
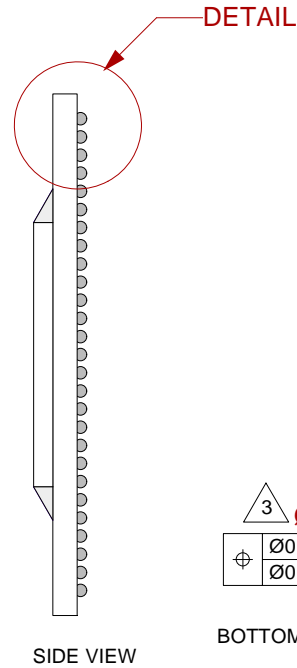
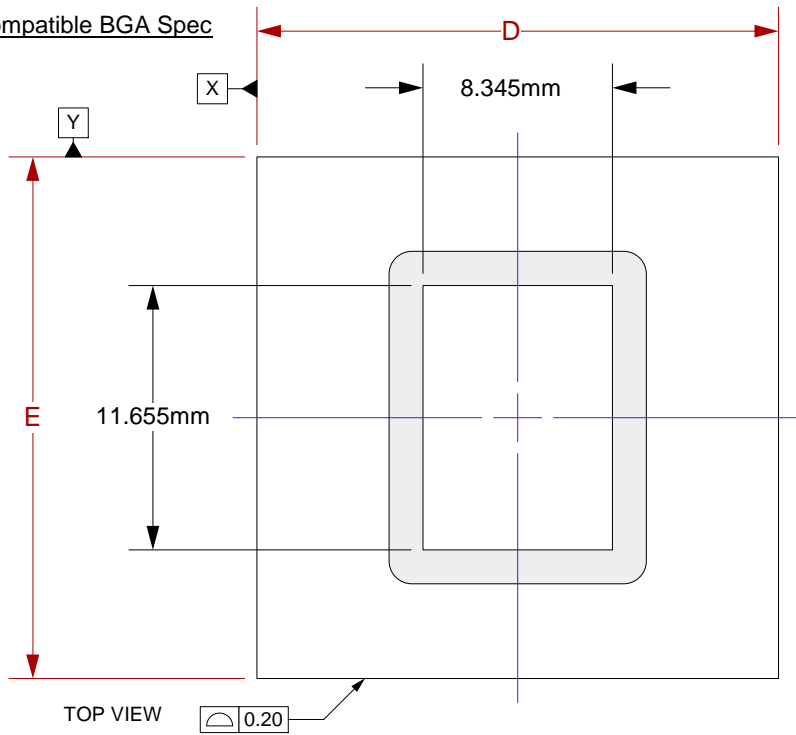
Target PCB Recommendations
Total thickness: 1.5mm min.
Plating: Gold or Solder finish

DXF DATA WILL BE PROVIDED

Recommended PCB Layout Tolerances:
±0.025mm [±0.001"] unless stated otherwise.

| | | | | |
|---|--|-----------------------|--------------|--------|
|  | CG-BGA-4007 Drawing | Status: Released | Scale: 3:1 | Rev: A |
| | © 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com | Drawing: Vinayak R | Date: 3/1/10 | |
| | | File: CG-BGA-4007 Dwg | Modified: | |


Compatible BGA Spec



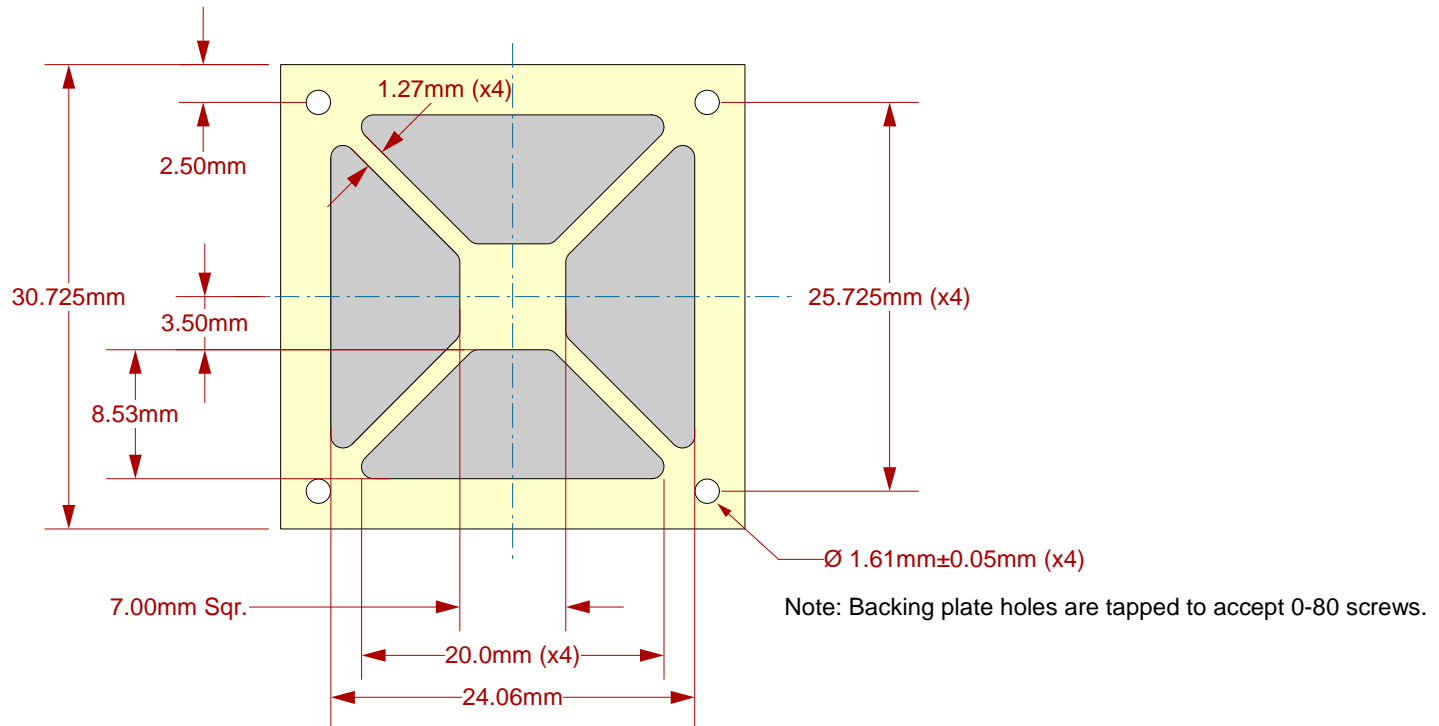
1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- △3 Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
 - △4 Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
 - △5 Parallelism measurement shall exclude any effect of mark on top surface of package.

| DIM | MIN | MAX |
|-----|----------|------|
| A | | 2.15 |
| A1 | 0.25 | 0.35 |
| b | | 0.50 |
| D | 23.0 BSC | |
| E | 23.0 BSC | |
| e | 0.8 BSC | |

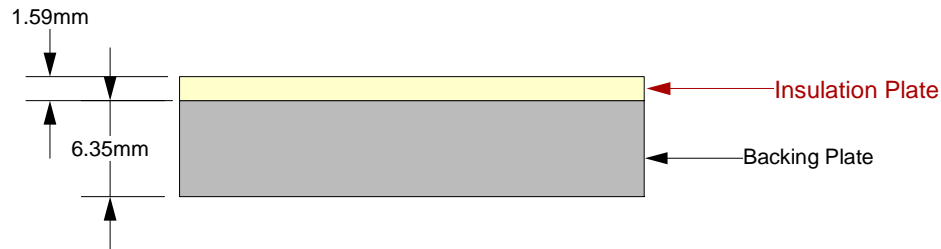
Array:27x27

| | | | |
|--|-----------------------|---------|--------------|
|  <p>CG-BGA-4007 Drawing © 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com</p> | Status: Released | Scale:- | Rev: A |
| | Drawing: Vinayak R | | Date: 3/1/10 |
| | File: CG-BGA-4007 Dwg | | Modified: |


Top View



Side View

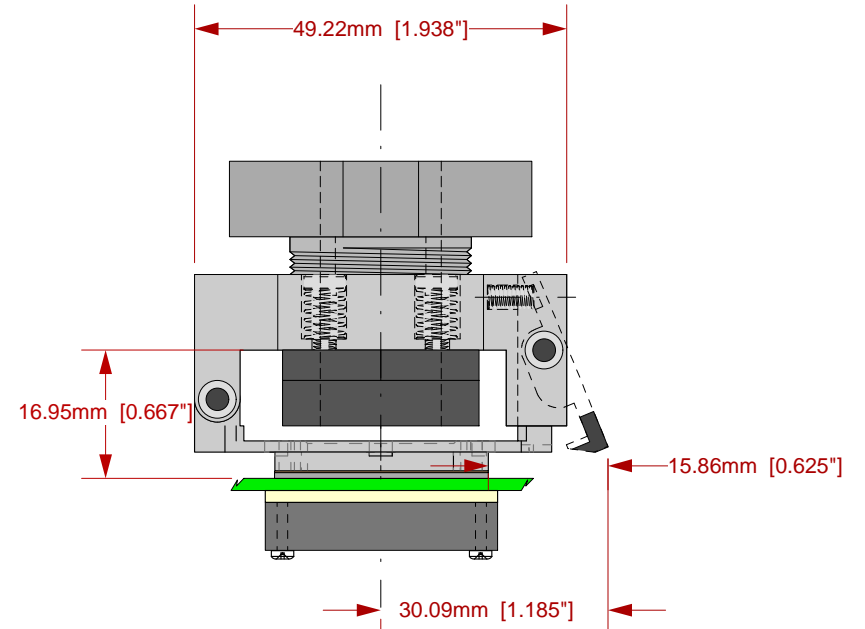
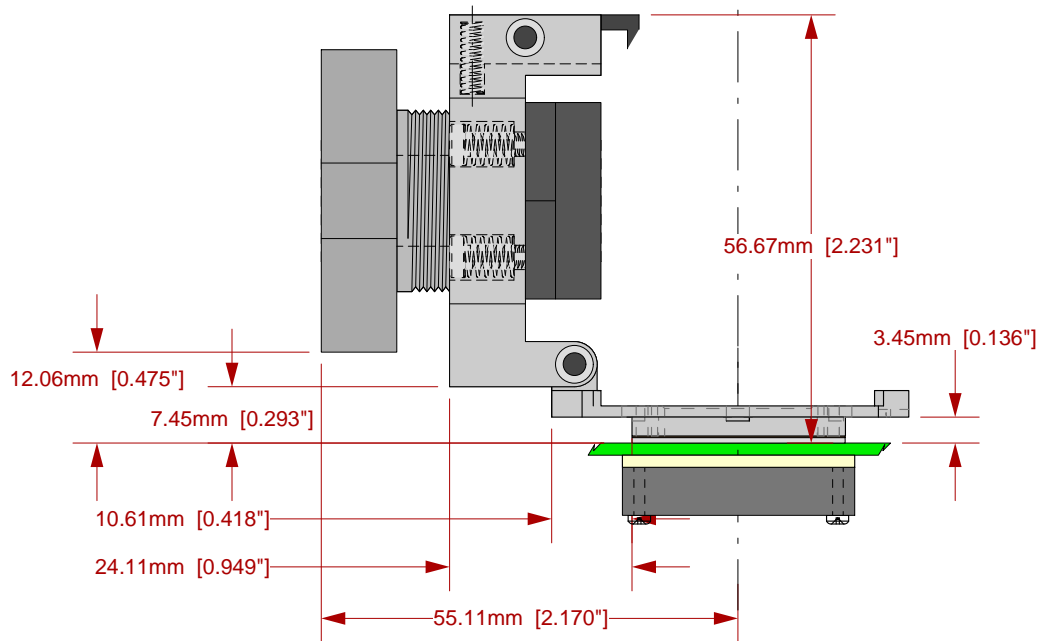
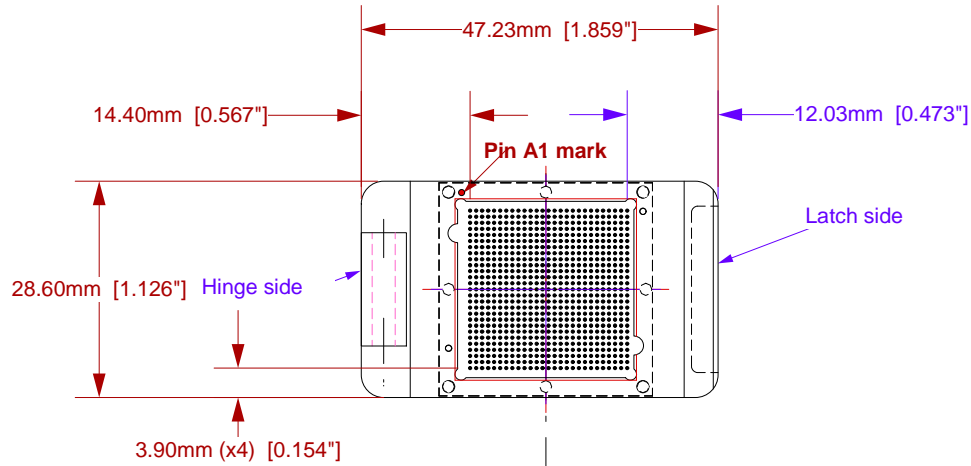


Description: Backing Plate with Insulation Plate


| | | | | |
|---|--|-----------------------|------------|--------------|
|  | CG-BGA-4007 Drawing © 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com | Status: Released | Scale: 2:1 | Rev: A |
| | | Drawing: Vinayak R | | Date: 3/1/10 |
| | | File: CG-BGA-4007 Dwg | | Modified: |

All dimensions are in mm.
 All tolerances are +/- 0.125mm.
 (Unless stated otherwise)

Top View of Socket Base



Description: Backing Plate with Insulation Plate

| | | | | |
|---|--|-----------------------|---------------|--------------|
|  | CG-BGA-4007 Drawing | Status: Released | Scale: 1.25:1 | Rev: A |
| | © 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com | Drawing: Vinayak R | | Date: 3/1/10 |
| | | File: CG-BGA-4007 Dwg | Modified: | |

All dimensions are in mm.
All tolerances are +/- 0.125mm.
(Unless stated otherwise)